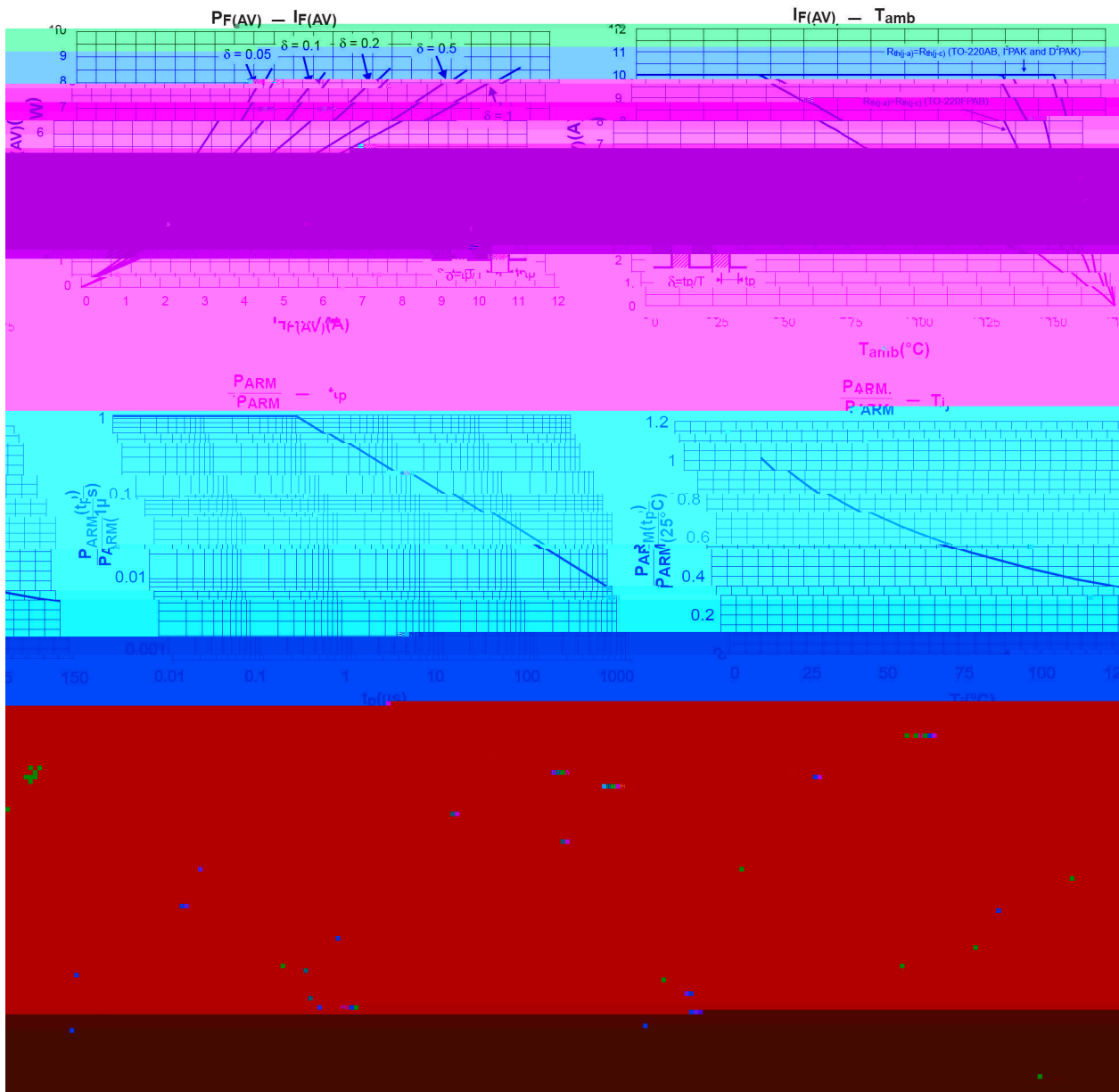


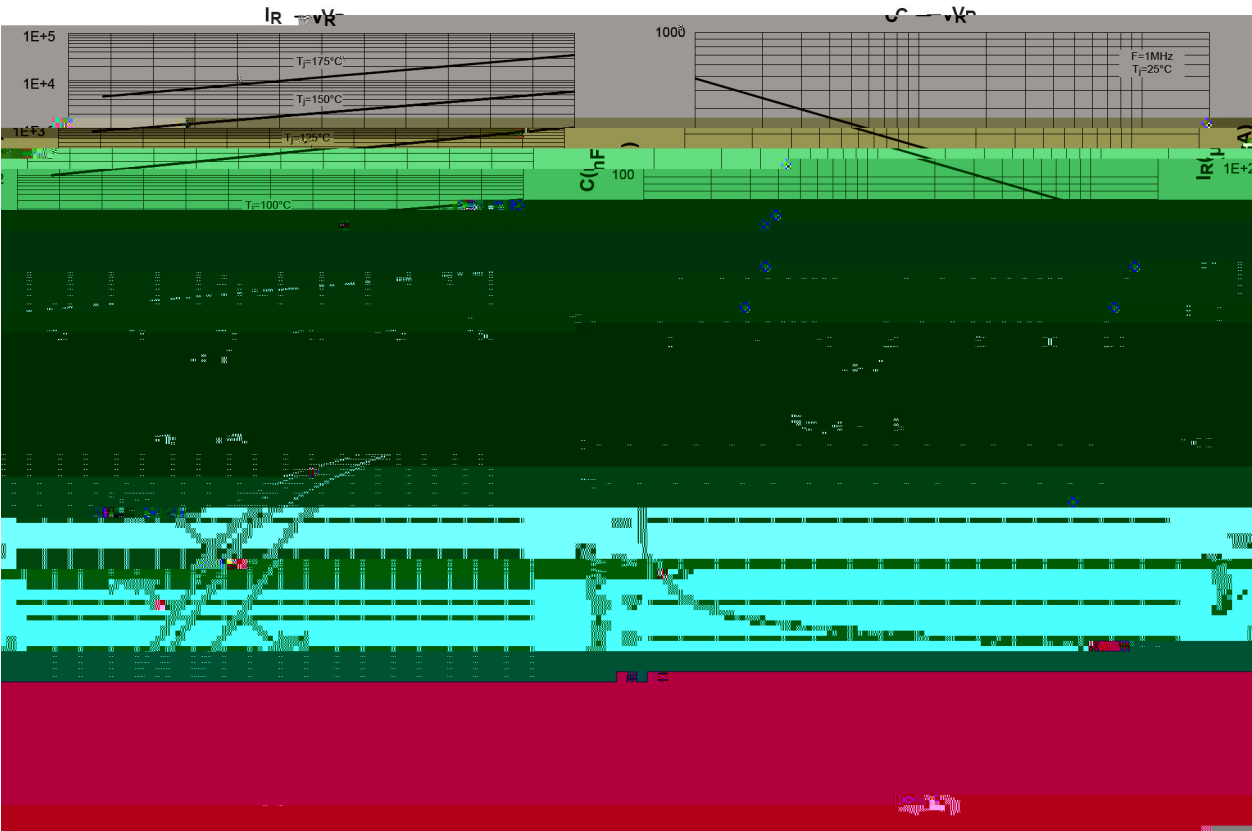
Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	150	V
RMS Forward Current	$I_{F(RMS)}$	30	A
Average Forward Current	$I_{F(AV)}$	10	A
Average Forward Current	$I_{F(AV)}$ total device	20	A
Non Repetitive Peak Surge Current	I_{FSM}	180	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	1.5	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	$I_F=10A(T_c=25^\circ C)$			0.9	V
		$I_F=10A(T_c=125^\circ C)$		0.69	0.75	V
		$I_F=20A(T_c=25^\circ C)$			1.0	V
		$I_F=20A(T_c=125^\circ C)$		0.79	0.86	V

/ Electrical Characteristic Curve

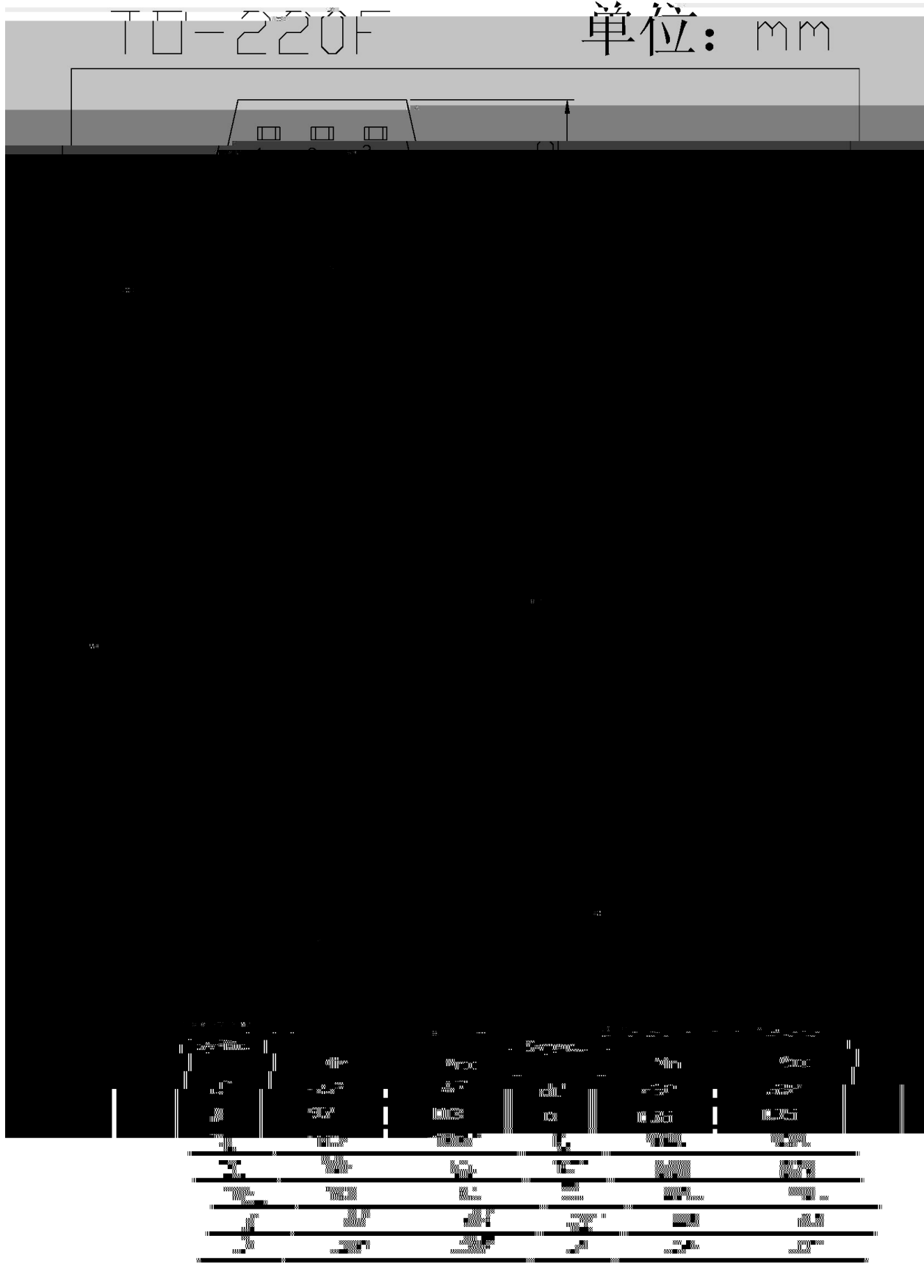


/ Electrical Characteristic Curve

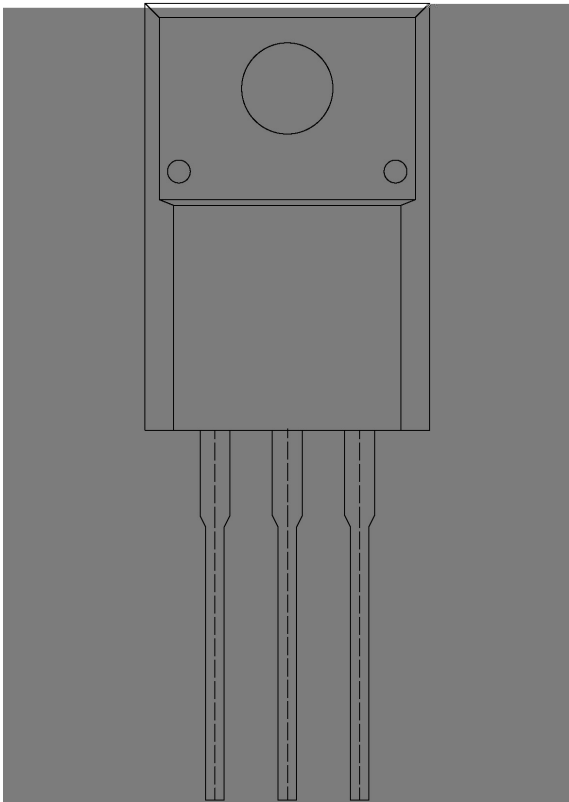




/ Package Dimensions



/ Marking Instructions



BR
MBRF20150
CT:

Note:

BR:	Company Code
MBRF20150:	Pr57d05ba6C t , code change with Lot No. 9 TD3.240 Tc8()Tj2

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

255±5

5±0.5sec;
- 3

2 10 /sec.
- 1.Preheating:25~150 , Time:60~90sec.

2.Peak Temp.:255±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5

10±1 sec.

Temp.:270±5

Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension		
	Units/Bag	Bags/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Bag	Inner Box	(unit mm ³) Outer Box